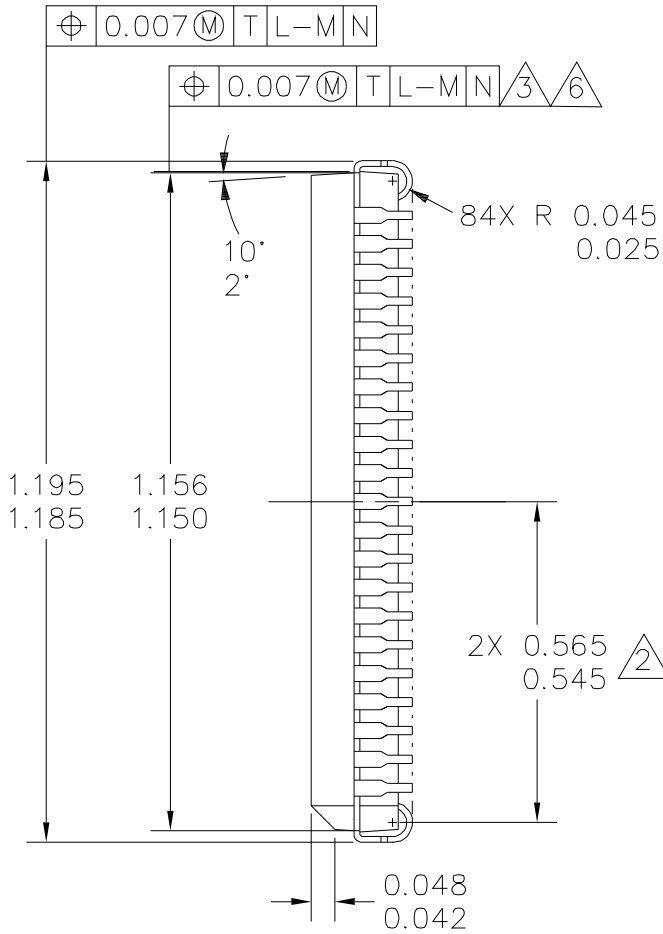
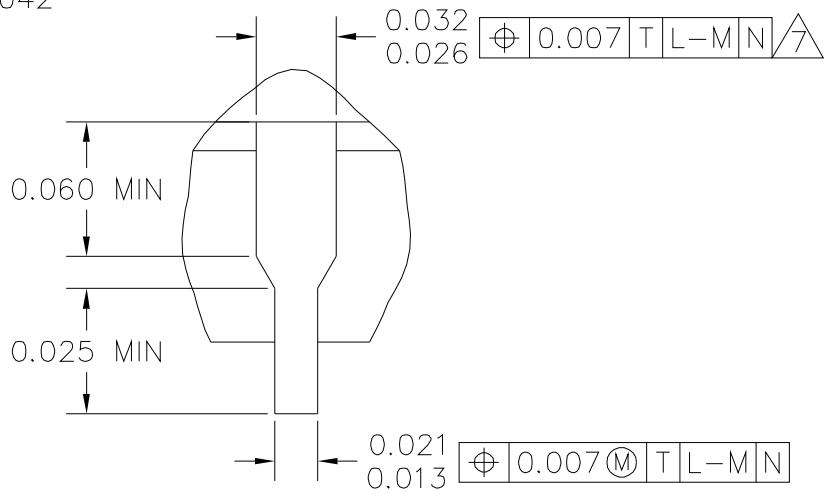


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NOTES:

1. DATUMS L, M AND N DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION TO BE MEASURED AT CLOSEST APPROACH OF LEAD TO DATUM T, SEATING PLANE.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS .010 PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO .012. DIMENSIONS ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH. TIE BAR BURRS, GATE BURRS, AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLACTIS BODY.
7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE DIMENSION TO BE GREATER THAN .037. THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE DIMENSION TO BE SMALLER THAN .025.

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